



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

A

A

B

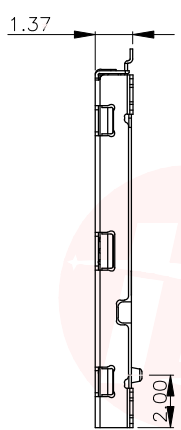
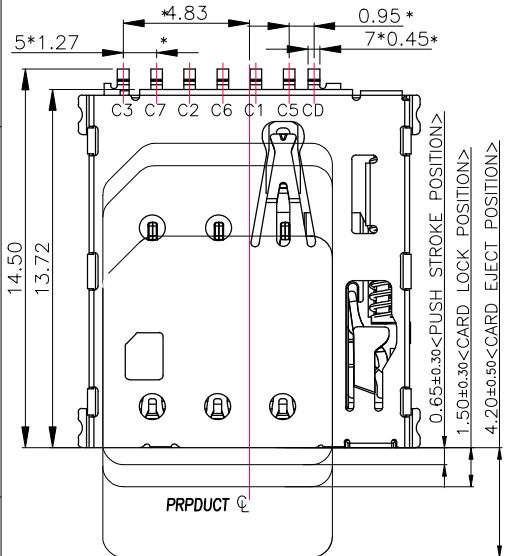
B

C

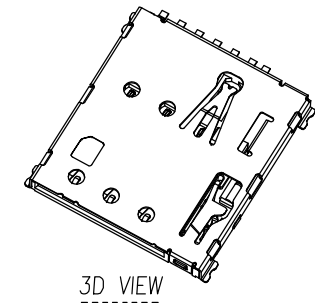
C

D

D

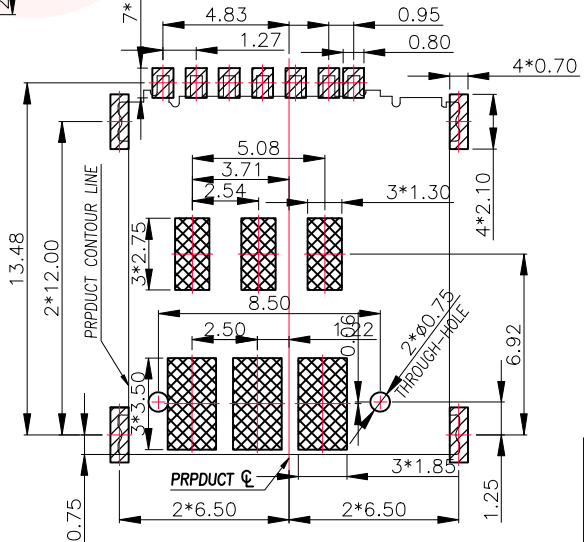
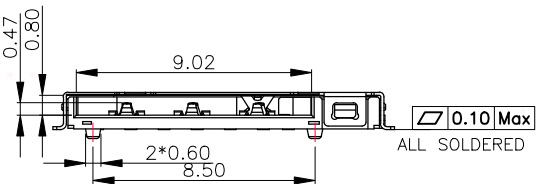


PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O

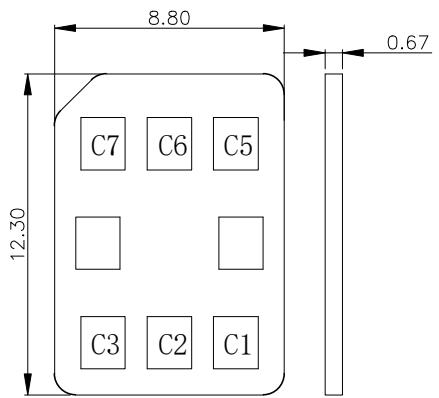
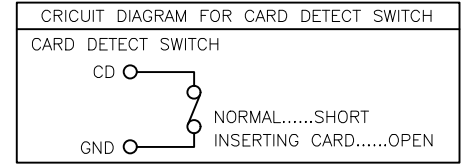


NOTES:

- MATERIAL:  
HOUSING: High Temperature Thermoplastic  
Terminal: Copper Alloy  
Shell: Stainless Steel
- PLATING:  
Terminal: 50u" Ni UNDERPLATED OVERALL  
G/F PLATED ON CONTACT AREA AND SOLDER AREA  
Shell: 30u" Ni UNDERPLATED OVERALL  
G/F PLATED ON CONTACT AREA AND SOLDER AREA
- TECHNICAL SPECIALITY:  
RATED VOLTAGE: 30V AC MAX.  
CURRENT RATING: 0.5A MAX.  
INSULATION RESISTANCE: 100MΩ MIN  
CONTACT RESISTANCE: 50mΩ MAX  
WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES  
OPERATING TEMPERATURE:  
-25°C~+85°C Humidity 80% R.H MAX
- DIMENSIONS WITH MARK \* MUST BE MEASURE BY QC AND IPQC



SMT SOLDER AREA  
 NO PATTERN AND VIA HOLE IN HTIS AREA



UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS:	ANGLES:	TITLE 1.37H NANO SIM CARD CONNECTOR	
X ±0.35	X° ±5°	DWN	xiong PART NO. SNO-1351A
X.X ±0.25	.X° ±3°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX ±0.15	X.X ±1°	APVD	wang SIZE: A4 SHEET:10F 1
		REV: A4	
CUSTOMER COPY			

1

2

3

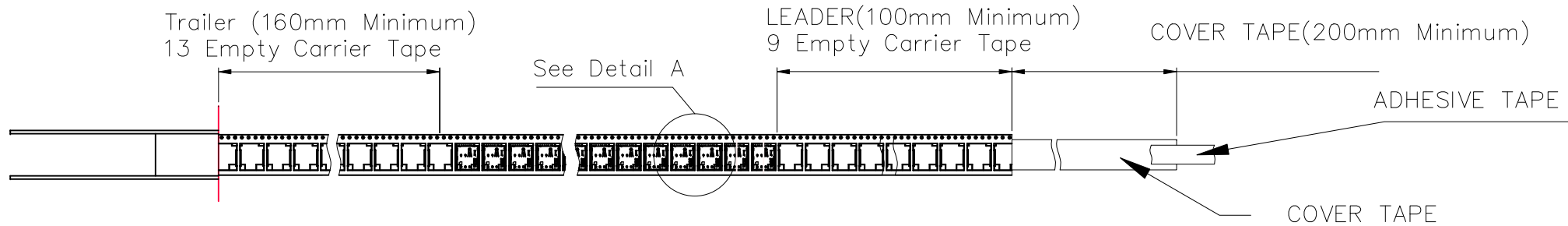
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5

6

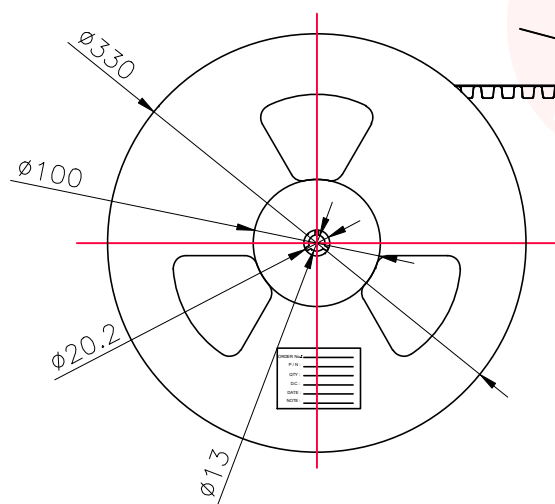


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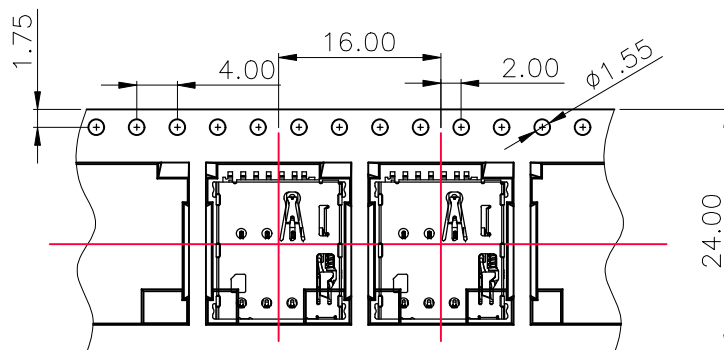
← PACKAGING DIRECTION      USER DIRECTION OF UNREELING →

COVER TAPE PEELING ANGLE: 165°~180°  
PEELING FORCE: 20~130g



← PACKAGING DIRECTION

→ USER DIRECTION OF UNREELING



DETAIL A

2	SNO-1351A	1500	10	15000	350X350X340
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UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X : ±0.35	X.° : ±5°
X.X : ±0.25	.X : ±3°
X.XX : ±0.15	X.X : ±1°



东莞市汉博电子科技有限公司  
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	1.37H NANO SIM CARD CONNECTOR		
DWN	xiong	PART NO. SNO-1351A	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:1OF 1
REV: A4			
CUSTOMER COPY			